

## SOT-23 Plastic-Encapsulate ESD Protection Diodes

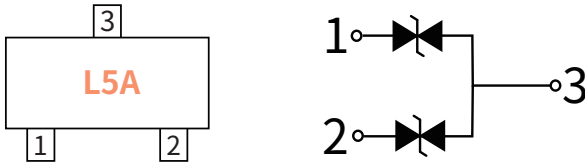
### Features

- Low leakage current
- SOT-23 surface mount package
- IEC 61000-4-2 (ESD Air):  $\pm 30\text{kV}$
- IEC 61000-4-2 (ESD Contact):  $\pm 30\text{kV}$
- IEC 61000-4-5 (Lightning 8/20 $\mu\text{s}$ ): 8A

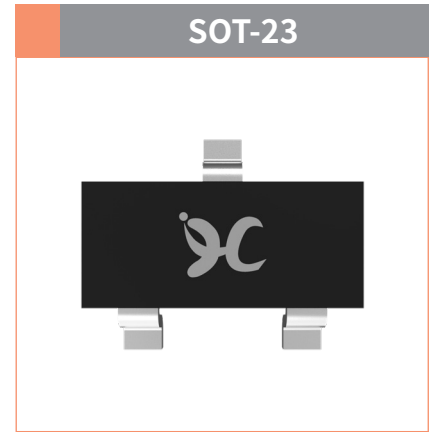
### Applications

- Automotive Applications
- CAN Bus
- Electronic Control Units
- Body Control Units
- ADAS Control Units
- PowerTrain Control Units

### Function Diagram



**Reverse Working Voltage**  
5V Max.  
**Normal capacitance**  
20pF(Max.)

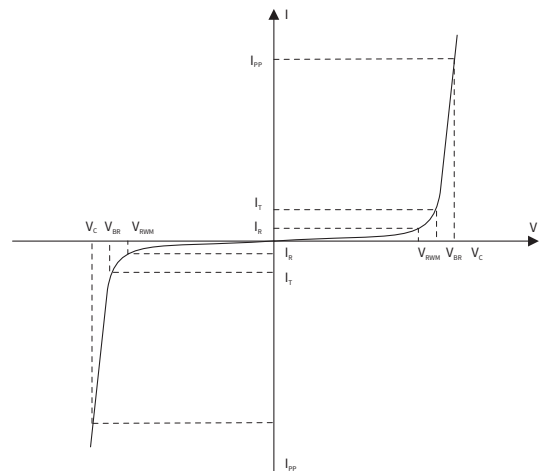


### Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V <sub>ESD</sub>	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2( Air )	$\pm 30$	KV
		ESD per IEC 61000-4-2( Contact)	$\pm 30$	KV
P <sub>PP</sub>	Peak Pulse Power	tp = 8/20 $\mu\text{s}$	95	W
I <sub>PP</sub>	Rated Peak Pulse Current	tp = 8/20 $\mu\text{s}$	8.0	A
T <sub>J</sub>	Operating JunctionTemperature Range	—	-55 to +125	°C
T <sub>STG</sub>	Operating JunctionTemperature Range	—	-55 to +150	°C

### Electrical Parameter

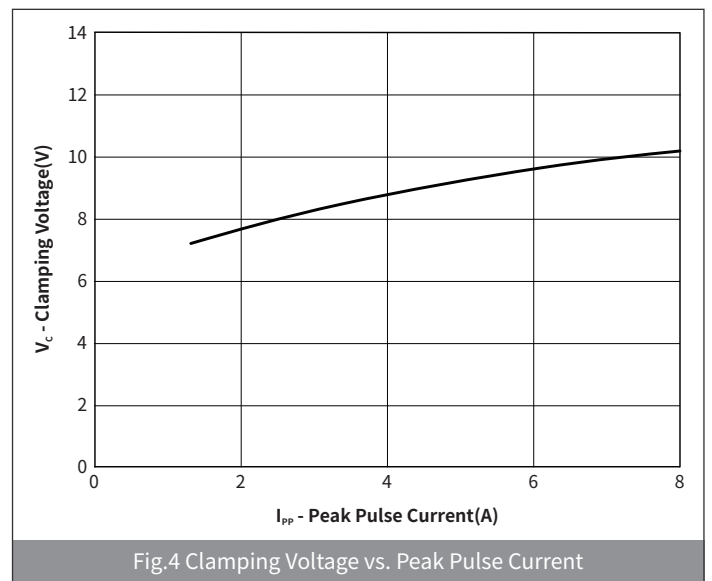
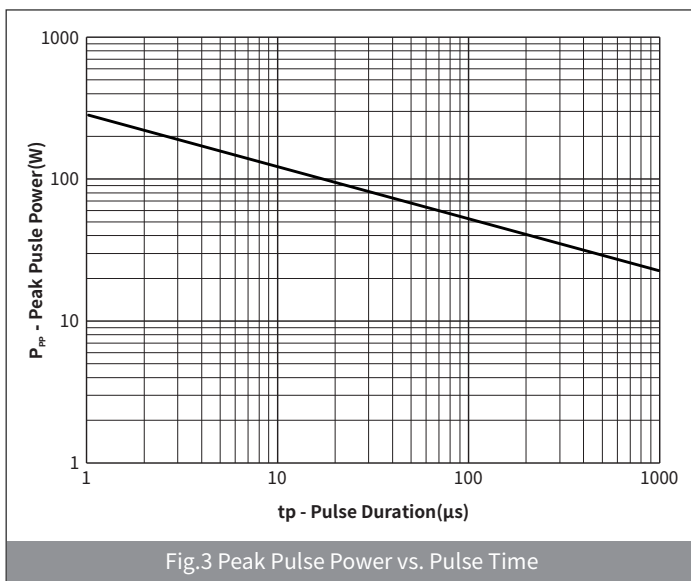
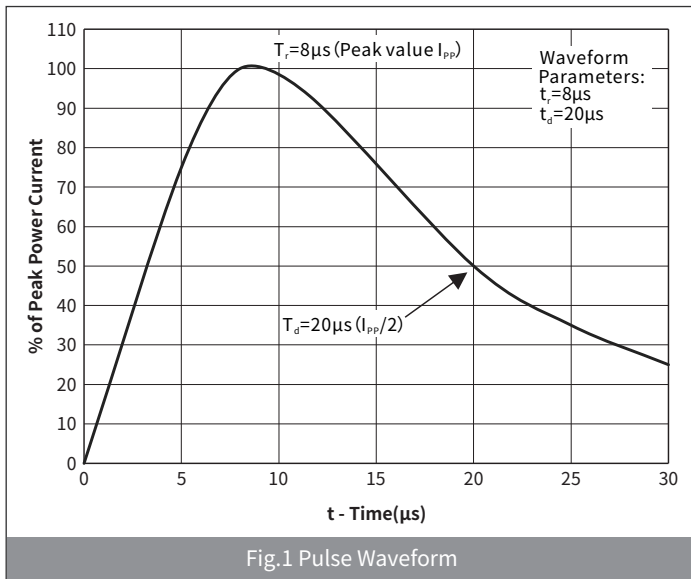
SYMBOL	PARAMETER
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>
I <sub>PP</sub>	Peak Pulse Current
I <sub>T</sub>	Test Current
I <sub>R</sub>	Reverse Leakage Current @ VRWM
V <sub>RWM</sub>	Peak Reverse Working Voltage
P <sub>PP</sub>	Peak Pulse Power Dissipation
C <sub>J</sub>	Junction Capacitance @ V <sub>R</sub> =0V,f=1MHz
I <sub>F</sub>	Forward Current
V <sub>F</sub>	Forward Voltage @I <sub>F</sub>



## Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	$V_{RWM}$	$T_a=25^\circ\text{C}$	—	—	5.0	V
Breakdown Voltage	$V_{BR}$	$I_R=1.0\text{mA}, T_a=25^\circ\text{C}$	5.6	—	8.0	V
Reverse Leakage Current	$I_R$	$V_R=5\text{V}, T_a=25^\circ\text{C}$	—	—	0.1	$\mu\text{A}$
Clamping Voltage	$V_C$	$I_{PP}=1.0\text{A}, t_p=8/20\mu\text{s}$	—	—	8.5	V
		$I_{PP}=8\text{A}, t_p=8/20\mu\text{s}$	—	—	12	
Junction Capacitance	$C_J$	$V_R=0\text{V}, f=1\text{MHz}$	—	—	20	pF

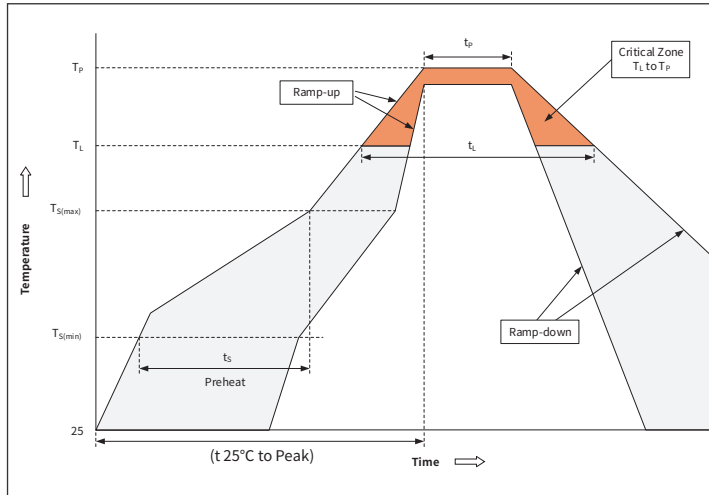
## Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)



## Ordering Information

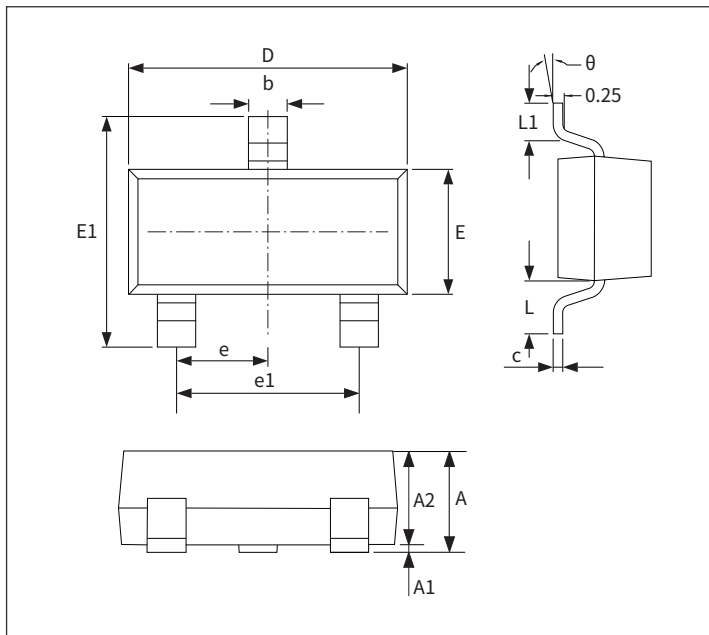
PREFERRED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
H5VNT2B	SOT-23	2.90×2.40×1.025	7" REEL	3000

## Recommended Soldering Conditions



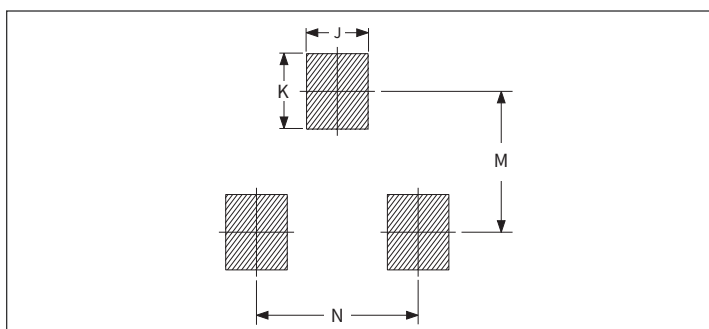
Profile Feature		Pb-Free Assembly
Pre-heat	Temperature Min ( $T_{S(min)}$ )	+150°C
	Temperature Max ( $T_{S(max)}$ )	+200°C
	Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{S(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	Temperature ( $T_L$ ) (Liquid us)	+217°C
	Temperature ( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		20-40secs
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C

## Package Outline Dimensions (SOT-23)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.15	0.035	0.045
A1	-	0.10	-	0.004
A2	0.90	1.05	0.035	0.041
b	0.30	0.50	0.012	0.020
c	0.10	0.20	0.004	0.008
D	2.80	3.00	0.110	0.118
E	1.20	1.40	0.047	0.055
E1	2.25	2.55	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.80	2.00	0.071	0.079
L	0.550REF		0.022REF	
L1	0.30	0.50	0.012	0.020
θ	-	8°	-	8°

## Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	0.75	0.85	0.030	0.033
K	0.85	0.95	0.033	0.037
M	1.95	2.05	0.077	0.081
N	1.85	1.95	0.073	0.077